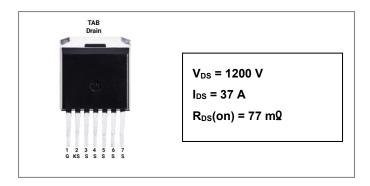
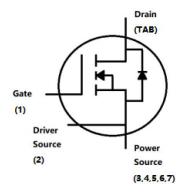




# S2M0080120J 1200V SIC POWER MOSFET



### **Circuit Diagram**



### **Description**

S2M0080120J is single SiC Power MOSFET packaged in TO-263-7 case. The device is a high voltage n-channel enhancement mode MOSFET that has very low total conduction losses and very stable switching characteristics over temperature extremes. The S2M0080120J is ideal for energy sensitive, high frequency applications in challenging environments.

#### **Features**

- · Positive temperature characteristics, easy to parallel.
- Low on-resistance Typ. RDS(on) = 77m<sup>\text{Q}</sup> .
- Fast switching speed and low switching losses.
- · Very fast and robust intrinsic body diode.
- Process of non-bright Tin electroplatin

### **Applications**

- EV Fast Charging Modules
- EV On Board Chargers
- Solar Inverters
- Online UPS/Industrial UPS
- SMPS (Switch Mode Power Supplies)
- DC-DC Converters
- ESS (Energy Storage Systems)

### Maximum Ratings(T=25°C unless otherwise specified)

| Characteristics          | Symbol               | Condition  | Max.        | Units |
|--------------------------|----------------------|--|-------------|-------|
| Drain Source Voltage     | V <sub>DSS</sub>     | V <sub>GS</sub> = 0V, I <sub>DS</sub> = 100uA, T <sub>j</sub> = 25°C | 1200        | V     |
| Gate Source Voltage      | V <sub>GSS</sub>     | T <sub>j</sub> = 25°C, Absolute maximum values, AC (f>1Hz)           | - 10 to +25 | V     |
| Gate Source Voltage      | V <sub>GSOP</sub>    | T <sub>j</sub> = 25°C Recommended Operational Values                 | -5 to +20   | V     |
| Continuous Drain Current | ID                   | V <sub>GS</sub> = 20V, T <sub>j</sub> = 25°C                         | 37          | А     |
|                          | I <sub>D</sub>       | V <sub>GS</sub> = 20V, T <sub>j</sub> = 100°C                        | 26          | А     |
| Pulsed Drain Current     | I <sub>D,pulse</sub> | Pulse width t <sub>P</sub> limited by T <sub>jmax</sub>              | 82          | Α     |
| Power Dissipation        | PD                   | T <sub>C</sub> =25°C, T <sub>J</sub> = 175 °C                        | 234         | W     |

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# **Electrical Characteristics(T=25℃ unless otherwise specified)**

| Characteristics                 | Symbol                     | Condition  | Min. | Тур. | Max. | Unit<br>s |  |
|---------------------------------|----------------------------|--|------|------|------|-----------|--|
| Drain Source Breakdown Voltage  | $V_{(BR)DSS}$              | $V_{GS} = 0V$ , $I_D = 1mA$  | 1200 |      |      | V         |  |
| 0 . 7                           |                            | $V_{DS} = V_{GS}$ , $I_D = 10$ mA  | 2.0  | 2.8  | 4.0  | V         |  |
| Gate Threshold Voltage          | $V_{GS(th)}$               | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 10mA, T <sub>J</sub> = 175 °C |      | 1.8  |      | V         |  |
| 7 0 1 1/1 5 1 0                 | I <sub>DSS</sub>           | V <sub>DS</sub> = 1200V, V <sub>GS</sub> = 0V                                      |      | 0.1  | 1.0  | uA        |  |
| Zero Gate Voltage Drain Current | I <sub>DSS</sub>           | V <sub>DS</sub> = 1200V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 175 °C             |      | 1    |      | uA        |  |
| 0-4- 0                          | I <sub>GSS+</sub>          | V <sub>GS</sub> = 20V, V <sub>DS</sub> = 0V  |      | 10   | 100  | nA        |  |
| Gate Source Leakage Current     | I <sub>GSS-</sub>          | V <sub>GS</sub> = -5V, V <sub>DS</sub> = 0V  |      | -10  | -100 | nA        |  |
| Drain Source On-State           | Б                          | V <sub>GS</sub> = 20V, I <sub>D</sub> = 20A  |      | 77   | 100  | mΩ        |  |
| Resistance                      | R <sub>DS(on)</sub>        | V <sub>GS</sub> = 20V, I <sub>D</sub> = 20A, T <sub>J</sub> = 175 °C               |      | 137  |      | mΩ        |  |
| To a second desidence           | <b>.e</b>                  | V <sub>DS</sub> = 20 V, I <sub>D</sub> = 20 A                                      |      | 10.5 |      | S         |  |
| Transconductance                | gfs                        | V <sub>DS</sub> = 20 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 175 °C             |      | 8    |      | S         |  |
| Input Capacitance               | C <sub>ISS</sub>           | V <sub>GS</sub> = 0V,  |      | 1324 |      |           |  |
| Output Capacitance              | Coss                       | V <sub>DS</sub> = 1000V  |      | 74   |      | pF        |  |
| Reverse Transfer Capacitance    | C <sub>RSS</sub>           | V <sub>AC</sub> = 25mV   |      | 3.4  |      |           |  |
| Coss Stored Energy              | Eoss                       | f = 200kHz   |      | 37   |      | uJ        |  |
| Turn-On Switching Energy        | Eon                        | V <sub>DS</sub> = 800V, V <sub>GS</sub> = -5/20V                                   |      | 290  |      |           |  |
| Turn-Off Switching Energy       | E <sub>OFF</sub>           | $I_D = 20A, R_{G(ext)} = 2.5\Omega$  |      | 20   |      | uJ        |  |
| Turn-On Delay Time              | $t_{\sf d(on)}$            | V <sub>DS</sub> = 800V, V <sub>GS</sub> = -5/20V                                   |      | 20   |      |           |  |
| Rise Time                       | t <sub>r</sub>             | $t_r$ $I_D = 20A, R_{G(ext)} = 2.5\Omega, L = 975uH$                               |      | 11   |      |           |  |
| Turn-Off Delay Time             | $t_{\text{d(off)}}$        | FWD=S2M0080120K  |      | 20   |      | ns        |  |
| Fall Time                       | t <sub>f</sub>             | 7  |      | 7.8  |      |           |  |
| Internal Gate Resistance        | R <sub>G(int)</sub>        | f = 1MHz, VAC = 25 mV, D-S short   |      | 3.3  |      | Ω         |  |
| Gate to Source Charge           | $Q_{gs}$                   | V <sub>DS</sub> = 800V, V <sub>GS</sub> = -5/20V                                   |      | 23   |      |           |  |
| Gate to Drain Charge            | $Q_{gd}$                   | <sub>3</sub> I <sub>D</sub> = 20A  |      | 14   |      | nC        |  |
| Total Gate Charge               | Gate Charge Q <sub>g</sub> |  |      | 54   |      |           |  |

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### **Reverse Diode Characteristics:**

| Characteristics                  | Symbol          | Condition   | Тур. | Max. | Units |
|----------------------------------|-----------------|---|------|------|-------|
| Diode Forward Voltage            | V <sub>SD</sub> | $V_{SD}$ $V_{GS}$ = -5V, $I_{SD}$ = 10A   |      |      | V     |
|                                  | V <sub>SD</sub> | V <sub>GS</sub> = -5V, I <sub>SD</sub> = 10A, T <sub>J</sub> = 175°C                | 3.5  |      | V     |
| Continuous Diode Forward Current | Is              | V <sub>GS</sub> = -5V, T <sub>C</sub> = 25°C  |      | 41   | Α     |
| Reverse Recovery Time            | t <sub>rr</sub> | t <sub>rr</sub> V <sub>GS</sub> = -5V, I <sub>SD</sub> = 20A, T <sub>J</sub> = 25°C |      |      | ns    |
| Reverse Recovery Charge          | Qrr             | V <sub>R</sub> = 800V   | 102  |      | nC    |
| Peak Reverse Recovery Current    | I <sub>mm</sub> | dif/dt= 1950A/µs  | 6.7  |      | Α     |

### **Thermal-Mechanical Specifications:**

| Characteristics                             | Symbol           | Condition    | Specification | Units |
|---|------------------|--------------|---------------|-------|
| Junction Temperature                        | TJ               | -            | -55 to +175   | °C    |
| Storage Temperature                         | T <sub>stg</sub> | -            | -55 to +175   | °C    |
| Typical Thermal Resistance Junction to Case | R <sub>eJC</sub> | DC operation | 0.64          | °C/W  |

### **Ordering Information:**

| Device      | Package  | Shipping    |
|-------------|----------|-------------|
| S2M0080120J | TO-263-7 | 800pcs/reel |

### **Marking Diagram**



Where XXXXX is YYWWL

S2M = Device Type  $0080 = R_{DS}(on)$ 

120 = Reverse Voltage (1200V)

 J
 = Package

 SSG
 = SSG

 YY
 = Year

 WW
 = Week

 L
 = Lot Number

Cautions: Molding resin

Epoxy resin UL:94V-0

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### **Ratings and Characteristics Curves**

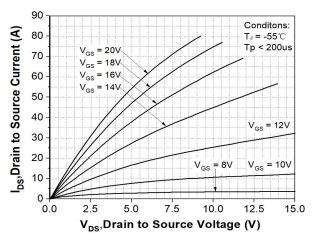


Figure 1. Output Characteristics T<sub>J</sub> = -55 °C

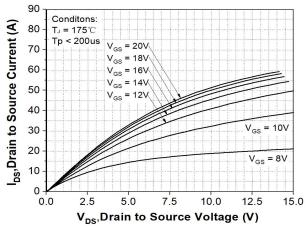


Figure 3. Output Characteristics T<sub>J</sub> = 175°C

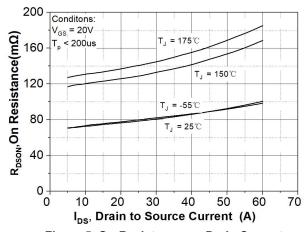


Figure 5. On-Resistance vs. Drain Current For Various Temperatures

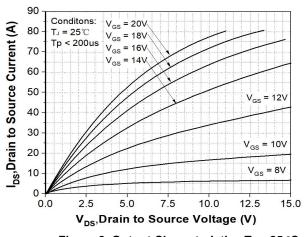


Figure 2. Output Characteristics T<sub>J</sub> = 25 °C

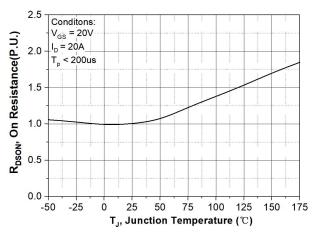


Figure 4. Normalized On-Resistance vs. Temperature

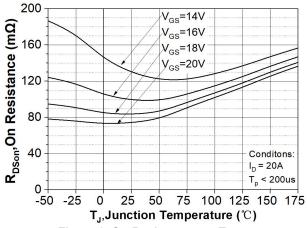


Figure 6. On-Resistance vs. Temperature For Various Gate Voltage

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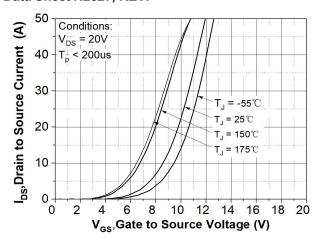


Figure 7. Transfer Characteristic for Various Junction Temperatures

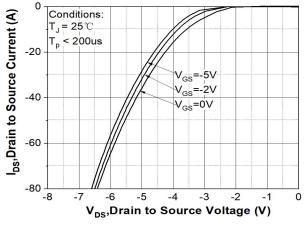


Figure 9. Body Diode Characteristic at T<sub>J</sub> = 25 °C

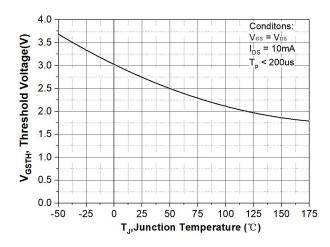


Figure 11. Threshold Voltage vs. Temperature



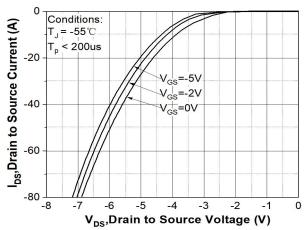


Figure 8. Body Diode Characteristic at T<sub>J</sub> = -55 °C

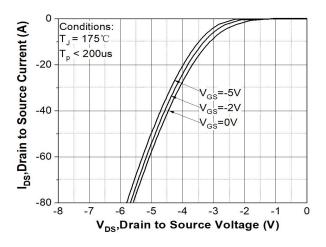


Figure 10. Body Diode Characteristic at T<sub>J</sub> = 175 °C

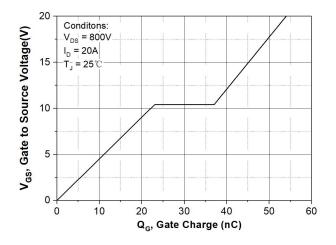


Figure 12. Gate Charge Characteristic

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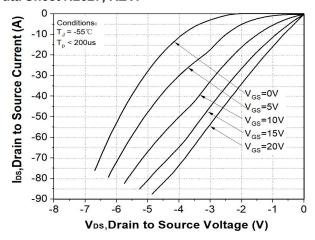


Figure 13. 3rd Quadrant Characteristic at T<sub>J</sub> = -55 °C

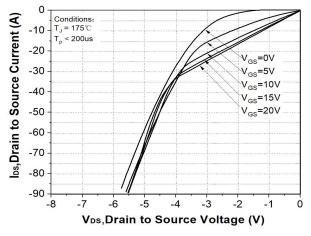


Figure 15. 3rd Quadrant Characteristic at T<sub>J</sub> = 175°C

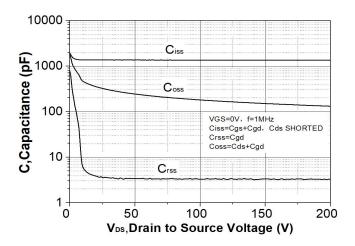


Figure 17. Capacitances vs. Drain-Source Voltage (0 - 200V)

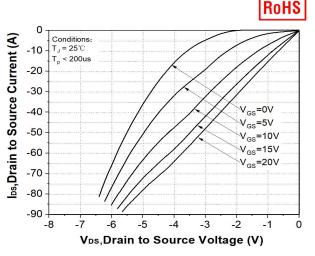


Figure 14. 3rd Quadrant Characteristic at T<sub>J</sub> = 25 °C

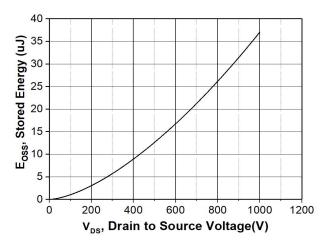


Figure 16. Output Capacitor Stored Energy

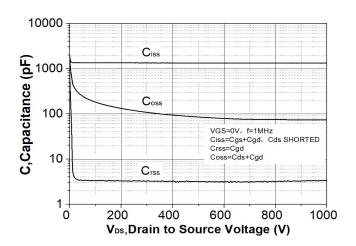


Figure 18. Capacitances vs. Drain-Source Voltage (0 - 1000V)

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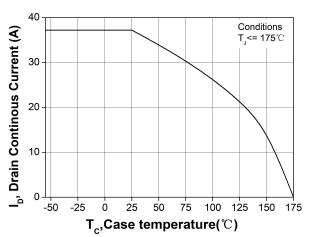


Figure 19. Continuous Drain Current Derating vs.

Case Temperature

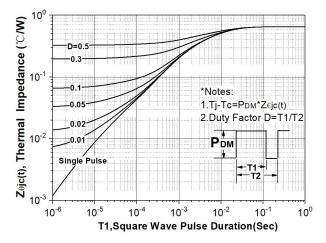


Figure 21. Transient Thermal Impedance (Junction - Case)

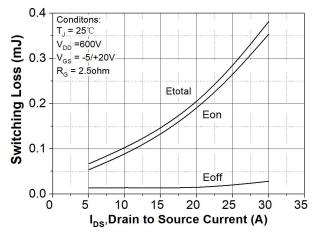


Figure 23. Clamped Inductive Switching Energy vs. Drain Current ( $V_{DD}$  = 600V)



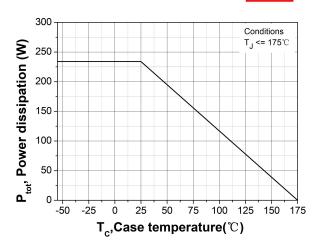


Figure 20. Maximum Power Dissipation Derating vs. Case Temperature

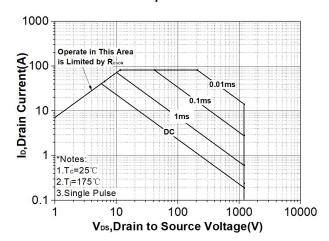


Figure 22. Safe Operating Area

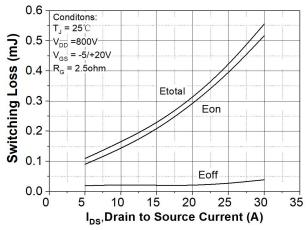


Figure 24. Clamped Inductive Switching Energy vs. Drain Current (V<sub>DD</sub> = 800V)

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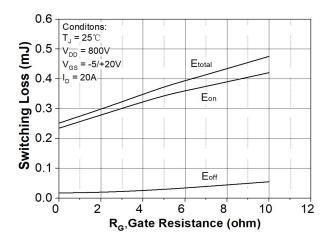


Figure 25. Clamped Inductive Switching Energy vs. R<sub>G(ext)</sub>

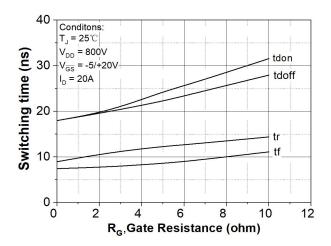


Figure 27. Switching Times vs. R<sub>G(ext)</sub>

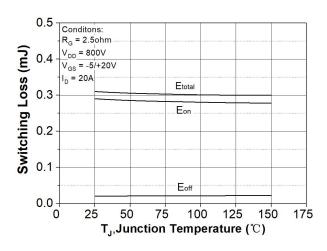


Figure 26. Clamped Inductive Switching Energy vs.
Temperature

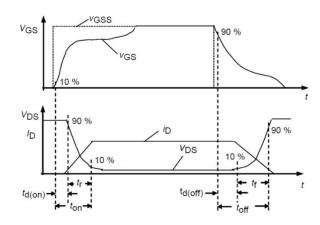
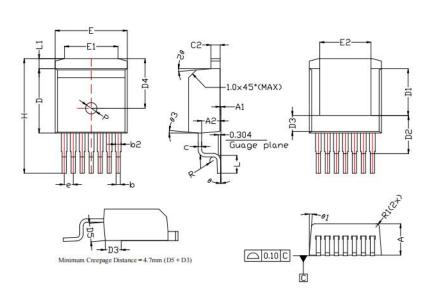


Figure 28. Switching Times Definition





### **Mechanical Dimensions TO-263-7**



| OVMDOL       | Millimeters |           |                |  |  |
|--------------|-------------|-----------|----------------|--|--|
| SYMBOL       | MIN.        | TYP.      | MAX.           |  |  |
| D            | 9.025       | 9.075     | 9.230          |  |  |
| Ē            | 10.13       | 10.18     | 10.23          |  |  |
| Α            | 4.30        | 4.435     | 4.57<br>17.313 |  |  |
| H<br>D1      | 15.000      | 16.178    | 17.313         |  |  |
| D1           | 4.65        | 6.60      | 6.70           |  |  |
| E1           | 6.50        | 7.55      | 8.60           |  |  |
| E2           | 6.778       | 7.233     | 7.655          |  |  |
| E2<br>D4     |             | 7.00 REF  |                |  |  |
| D5           | 1.900       | 2.605     | -              |  |  |
| A1           | 0           | 0.125     | 0.25           |  |  |
| A2           |             | 2.595 REF |                |  |  |
| е            |             | 1.27 TYP  |                |  |  |
| L            | 2.324       | 2.512     | 2.70           |  |  |
| b<br>L1      | 0.50        | 0.60      | 0.70           |  |  |
| L1           | 0.968       | 1.418     | 1.868          |  |  |
| l h2         | 0.60        |           |                |  |  |
| C2           | 1.17        | 1.27      | 1.40           |  |  |
| C2<br>c<br>R |             |           | 0.600          |  |  |
| R            | 0.506 REF   |           |                |  |  |
| R1           | 0.50 REF    |           |                |  |  |
| Р            | ø1.60 REF   |           |                |  |  |
| θ            | 0° 1° 4°    |           |                |  |  |
| Θ1           | 3°          | 5.5°      | 7°             |  |  |
| Θ2           | 3°          | 5°        | 7°             |  |  |
| Θ3           | 3°          | 5°        | 7°             |  |  |

#### S2M0080120J



### Technical Data Data Sheet N2527, REV.-



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DMN2080UCB4-7 DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 DMP22D4UFO-7B DMN1006UCA6-7 DMN16M9UCA6-7
STF5N65M6 IRF40H233XTMA1 STU5N65M6 DMN6022SSD-13 DMN13M9UCA6-7 DMTH10H4M6SPS-13 DMN2990UFB-7B
IPB80P04P405ATMA2 2N7002W-G MCAC30N06Y-TP MCQ7328-TP BXP7N65D BXP4N65F AOL1454G WMJ80N60C4 BXP2N20L
BXP2N65D BXT1150N10J BXT1700P06M TSM60NB380CP ROG RQ7L055BGTCR DMNH15H110SK3-13 SLF10N65ABV2
BSO203SP BSO211P IPA60R230P6 IPA60R460CE